



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

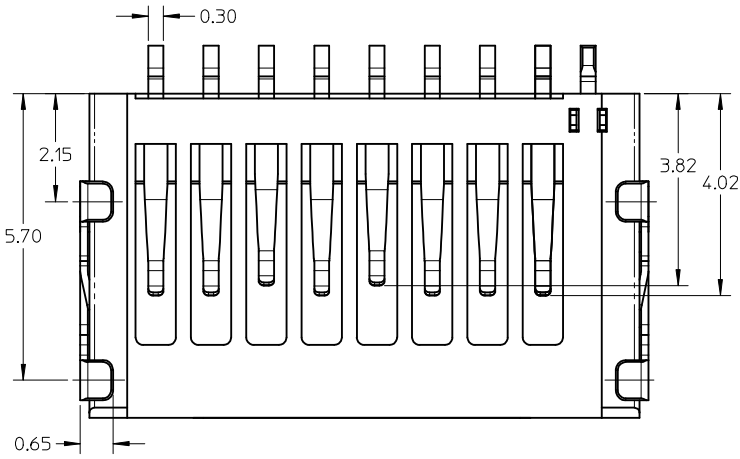
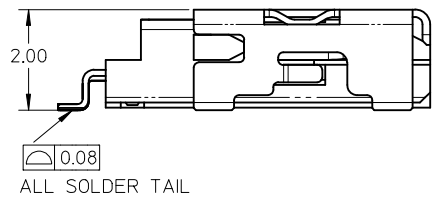
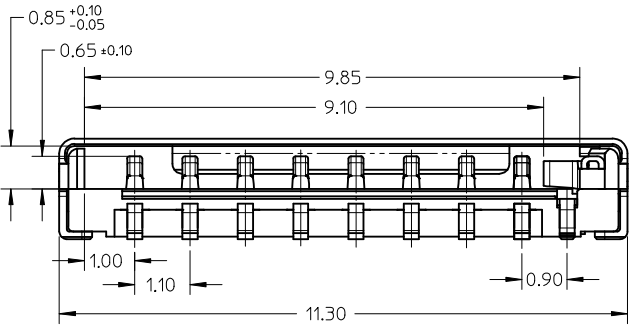
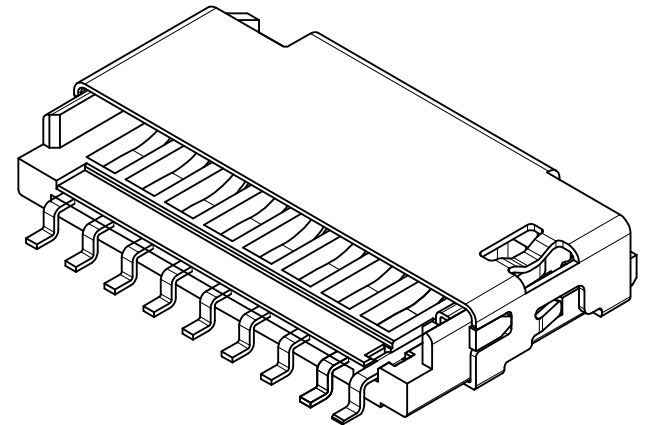
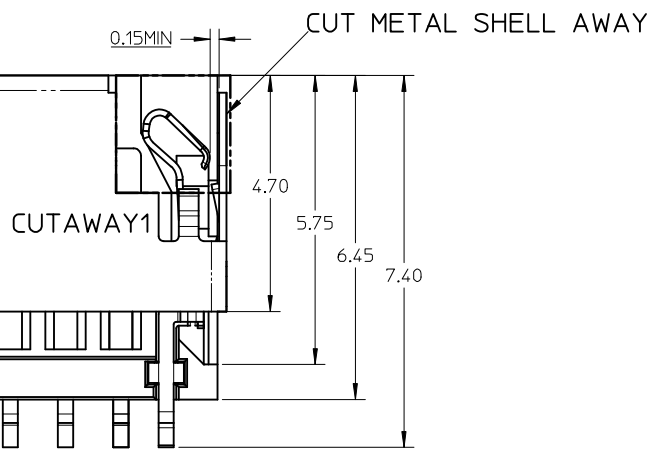
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



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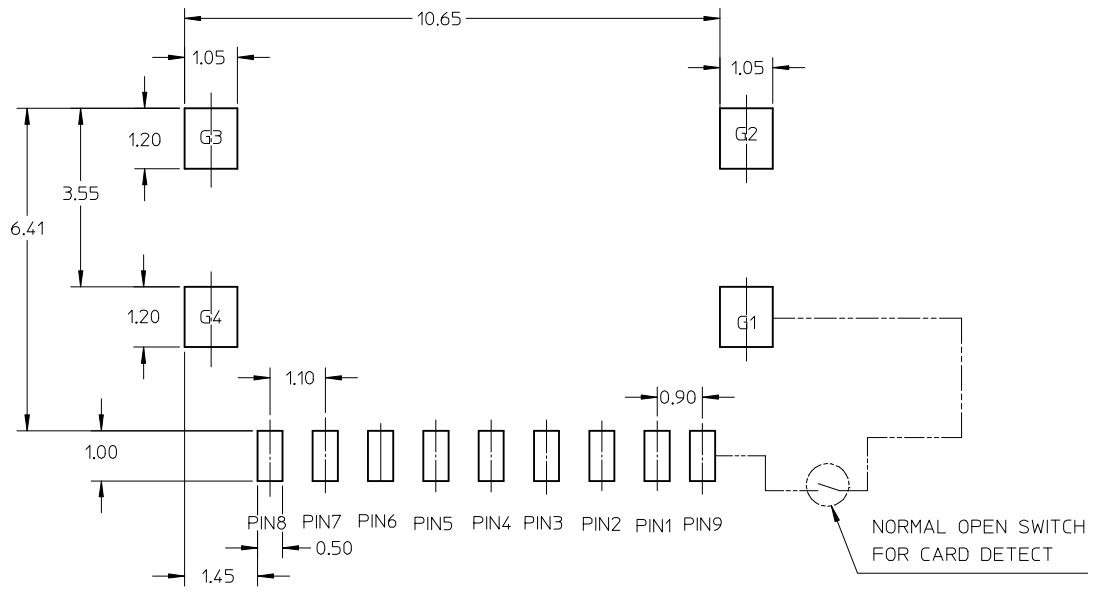


- NOTES:
- MATERIAL:
 - 1-1 HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL 94V-0, BLACK
 - 1-2 SIGNAL TERMINAL AND DETECT TERMINAL: PHOSPHOR BRONZE
 - 1-3 METAL SHELL: STAINLESS STEEL
 - FINISH:
 - 2-1 SIGNAL TERMINAL: 1.25 MICRON NICKEL MIN UNDER-PLATED, CONTACT AREA SEE TABLE, GOLD FLASH ON SOLDER AREA.
 - 2-2 METAL SHELL: GOLD FLASH PLATED AT SOLDER PAD AREA.
 - 2-3 DETECT PIN: 1.25 MICRON NICKEL MIN UNDER-PLATED, 0.38 MICRON MIN GOLD PLATING ON CONTACT AREA, GOLD FLASH ON SOLDER AREA.
 - PRODUCT SPECIFICATION: PS-105078-001.
 - PACKAGE SPECIFICATION: PK-105078-001.
 - PRODUCT COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

105149-0101	0.38 MICRON MIN. GOLD PLATING
105149-0001	0.76 MICRON MIN. GOLD PLATING
105149-1001	0.1 MICRON MIN. GOLD PLATING
P/N	CONTACT AREA PLATING

REVISED EC NO: SH2013-0296 DRW:GLL 2013/03/22 CHKD: APPR:AYIN 2013/04/08 REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	$F_A=0$	mm	INCH	DRAWN BY LIU LEI	DATE 2008/8/10	TITLE 2.0H TFR HEADER WITH SIDE DETECT PIN		
	$F_C=0$	4 PLACES ± ---	± ---	CHECKED BY WFDENG	DATE 2008/8/10	MOLEX INCORPORATED		
	$F_P=0$	2 PLACES ± 0.15	± ---	APPROVED BY WFDENG	DATE 2010/02/11	DOCUMENT NO. SD-105149-001	SHEET NO. 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ± 2 °		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

9 8 7 6 5 4 3 2 1



G4	GND
G3	GND
G2	GND
G1	GND
P9	DET
P8	DAT1
P7	DAT0
P6	VSS
P5	CLK
P4	VDD
P3	CMD
P2	CD/DAT3
P1	DAT2
NAME	TYPE
PIN ASSIGNMENT	

RECOMMEND PCB LAYOUT
RECOMMEND TOLERANCE: +/-0.05 MM

NORMAL OPEN SWITCH
FOR CARD DETECT

SEE SHEET 1 EC NO: SH2013-0296 DRWNG: GLL1 CH/KD: APPR: AY/IN REV:	2013/03/22 2013/04/08	QUALITY SYMBOLS $\nabla_F = 0$ $\nabla_E = 0$ $\nabla_A = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.15 ± --- 1 PLACE ± 0.20 ± --- ANGULAR ± 2°	DIMENSION STYLE MM ONLY DRAWN BY: LIU LEI CHECKED BY: WFDENG APPROVED BY: WFDENG MATERIAL NO.	SCALE: 1:1 DESIGN UNITS: METRIC DATE: 2008/8/10 DATE: 2008/8/10 DATE: 2010/02/11	THIRD ANGLE PROJECTION TITLE: 2.0H TFR HEADER WITH SIDE DETECT PIN MOLEX INCORPORATED DOCUMENT NO. SD-105149-001	SHEET NO. 2 OF 2
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE SHEET 1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		